Authorized Representative*  Title - Representative  Phone - Representative*  Email - Representative*	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.					
Company name* Company unique ID Unique ID Authority  Response Date* 2024-05-08  Contact Name Product Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onse Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UC3844BVD1R2G ANA SMPS PWM CONTROLLER 2024-05-08 PH1 71.99 mg	rials and Mfg Information					
2024-05-08   202						
Title - Contact Name Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards P	Response Date*					
Product Enviro Compliance Authorized Representative* Title - Representative Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UC3844BVD1R2G ANA SMPS PWM CONTROLLER 2024-05-08 Product-Env-Stewards@onse						
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name  UC3844BVD1R2G ANA SMPS PWM CONTROLLER  Phone - Representative* NA Product-Env-Stewards@onse Weight* UOM PH1 71.99 mg	Email - Contact*					
Product-Env-Stewards    Product Enviro Compliance   NA   Product-Env-Stewards@onset	Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UC3844BVD1R2G ANA SMPS PWM CONTROLLER 2024-05-08 PH1 71.99 mg	Email - Representative*					
UC3844BVD1R2G ANA SMPS PWM CONTROLLER 2024-05-08 PH1 71.99 mg	Product-Env-Stewards@onsemi.com					
	Unit Type					
Janufacturing Proccess Information	Each					
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflo	Cycles					
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Lycies					
omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds						
or more information regarding material composition please refer to page 3						

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.06	mg
			Supplier	Silver (Ag)	7440-22-4		1.92	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.156	mg
			Supplier	Acrylic resins	Proprietary Data		0.264	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.2257	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.4441	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58	58 mg		Proprietary	proprietary data		2.2864	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.1507	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.18	mg	Supplier	Palladium (Pd)	7440-05-3		0.0029	mg
			Supplier	Copper (Cu)	7440-50-8		0.1771	mg